

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

SECURITY AGREEMENT

CONVEYING PARTY DATA

Name	Execution Date
Wafer Holdings, Inc.	09/26/2008

RECEIVING PARTY DATA

Name:	PNC Bank, National Association
Street Address:	500 First Avenue
Internal Address:	Commercial Loan Service Center/DDC
City:	Pittsburgh
State/Country:	PENNSYLVANIA
Postal Code:	15219

PROPERTY NUMBERS Total: 93

Property Type	Number
Patent Number:	6817369
Patent Number:	6722056
Patent Number:	6145520
Patent Number:	6907890
Patent Number:	4571850
Patent Number:	6766818
Patent Number:	6837944
Patent Number:	6286688
Patent Number:	6805754
Patent Number:	6647641
Patent Number:	5954068
Patent Number:	5902402
Patent Number:	6240938
Patent Number:	6269822

PATENT

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Patent Number:	6843859
Patent Number:	6523552
Patent Number:	5807408
Patent Number:	6871657
Patent Number:	6928751
Patent Number:	6923192
Patent Number:	6754980
Patent Number:	7100304
Patent Number:	6684890
Patent Number:	7047989
Patent Number:	7156111
Patent Number:	7104268
Patent Number:	5625249
Patent Number:	5247954
Patent Number:	6679272
Patent Number:	6892738
Patent Number:	7287537
Patent Number:	5365960
Patent Number:	6532974
Patent Number:	6626189
Patent Number:	6842998
Patent Number:	6928750
Patent Number:	5556479
Patent Number:	6607607
Patent Number:	6767877
Patent Number:	6261845
Patent Number:	5972123
Patent Number:	6840250
Patent Number:	6818563
Patent Number:	5234540
Patent Number:	7169253
Patent Number:	7185661
Patent Number:	5656097
Patent Number:	5908509
Patent Number:	5996595

Patent Number:	5950645
Patent Number:	6378534
Patent Number:	5148823
Patent Number:	5090432
Patent Number:	5286657
Patent Number:	6955727
Patent Number:	6189552
Patent Number:	7311847
Patent Number:	6649018
Patent Number:	6863836
Patent Number:	6328809
Patent Number:	5226242
Patent Number:	6039059
Patent Number:	6140744
Patent Number:	6463938
Patent Number:	6681782
Patent Number:	6684891
Patent Number:	7117876
Patent Number:	7268469
Patent Number:	7211932
Application Number:	11625556
Application Number:	61034142
Application Number:	11755619
Application Number:	11625651
Application Number:	11837292
Application Number:	11777256
Application Number:	11595029
Application Number:	11873750
Application Number:	61031845
Application Number:	12070620
Application Number:	11781835
Application Number:	11649535
Application Number:	60985947
Application Number:	11640718
Application Number:	11745866

Application Number:	11624445
Application Number:	11841427
Application Number:	10585229
Application Number:	11544802
Application Number:	12059602
Application Number:	11454447
Application Number:	11777252
Application Number:	11839885
Application Number:	09324813

CORRESPONDENCE DATA

Fax Number: (202)408-3141

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 202-408-3121 x2348

Email: jpaterso@cscinfo.com

Correspondent Name: Corporation Service Company

Address Line 1: 1090 Vermont Avenue NW, Suite 430

Address Line 2: Attn: Jean Paterson

Address Line 4: Washington, DISTRICT OF COLUMBIA 20005

ATTORNEY DOCKET NUMBER:	768477
NAME OF SUBMITTER:	Jean Paterson

Total Attachments: 14

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EXPORT-IMPORT TRADEMARK AND PATENT SECURITY AGREEMENT

THIS EXPORT-IMPORT TRADEMARK AND PATENT SECURITY AGREEMENT (the "Agreement") made as of this 26th day of September, 2008 by WAFER HOLDINGS, INC., a Delaware corporation ("Grantor"), in favor of PNC BANK, NATIONAL ASSOCIATION, in its capacity as agent ("Agent") for the Lenders:

W I T N E S S E T H

WHEREAS, Grantor has entered into that certain Export-Import Revolving Credit and Security Agreement with Agent and the financial institutions party thereto from time to time as lenders (the "Lenders") dated as of the date hereof (as same may be amended, restated, supplemented or modified from time to time, the "Loan Agreement") providing for the extensions of credit to be made to Borrowers by Lenders;

WHEREAS, Grantor has granted to Agent, for the benefit of Lenders, a security interest in substantially all of the assets of Grantor including all right, title and interest of Grantor in, to and under all now owned and hereafter acquired trademarks and patents, together with the goodwill of the business symbolized by Grantor's trademarks and patents and all products and proceeds thereof, to secure the payment of all amounts owing by Borrowers under the Loan Agreement;

NOW, THEREFORE, in consideration of the premises set forth herein and for other good and valuable consideration, receipt and sufficiency of which are hereby acknowledged, Grantor agrees as follows:

1. Incorporation of Loan Agreement. The Loan Agreement and the terms and provisions thereof are hereby incorporated in their entirety by this reference. All terms capitalized but not otherwise defined herein shall have the same meanings ascribed to them in the Loan Agreement.

2. Grant and Reaffirmation of Grant of Security Interests To secure the payment and performance of the Obligations, Grantor hereby grants to Agent, for its benefit and the benefit of Lenders, and hereby reaffirms its prior grant pursuant to the Loan Agreement of a continuing security interest in Grantor's entire right, title and interest in and to the following whether now owned or existing or hereafter created, acquired or arising:

(i) each trademark and patent listed on Schedule 1 annexed hereto, (such trademarks and patents, the "Trademarks" and "Patents") together with any reissues, continuations or extensions thereof, and all of the goodwill of the business connected with the use of, and symbolized by, each Trademark; and

(ii) all products and proceeds of the forgoing, including without limitation, any claim by Grantor against third parties for past, present or future (a) infringement or dilution of any Trademark or Patent, or (b) injury to the goodwill associated with any Trademark.

3. Representations and Warranties. Grantor hereby represents and warrants that the Trademarks and Patents listed on Schedule I attached hereto constitute all trademarks and patents owned or registered to Grantor as of the date of this Agreement.

[signatures to appear on following page]

IN WITNESS WHEREOF, Grantor has duly executed this Agreement as of the date first written above.

WAFER HOLDINGS, INC.

By: As (Scanned)
Name: Adam Schmitt
Title: Director

Agreed and Accepted
As of the Date First Written Above

PNC BANK, NATIONAL ASSOCIATION,
as Agent

By: _____
Name: _____
Title: _____

[SIGNATURE PAGE TO EXPORT-IMPORT TRADEMARK AND PATENT PROPERTY
SECURITY AGREEMENT]

PATENT
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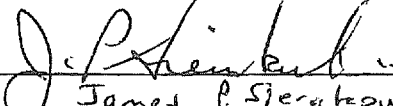
IN WITNESS WHEREOF, Grantor has duly executed this Agreement as of the date first written above.

WAFER HOLDINGS, INC.

By: _____
Name: _____
Title: _____

Agreed and Accepted
As of the Date First Written Above

PNC BANK, NATIONAL ASSOCIATION,
as Agent

By: 
Name: James P. Sierakowski
Title: Vice President

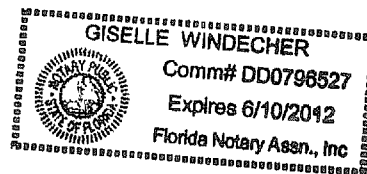
[SIGNATURE PAGE TO EXPORT-IMPORT TRADEMARK AND PATENT PROPERTY
SECURITY AGREEMENT]

COMPANY ACKNOWLEDGMENT

UNITED STATES OF AMERICA :
STATE OF Florida : SS
COUNTY OF Maricopa :

On this 22 of September, 2008, before me personally appeared Adam Schindel to me known and being duly sworn, deposes and says that s/he is authorized to sign on behalf of Wafer Holdings, Inc., that s/he signed the Agreement thereto pursuant to the authority vested in him by law; that the within Agreement is the voluntary act of such company; and s/he desires the same to be recorded as such.

Giselle Windecher
Notary Public
My Commission Expires: 6/10/12



(ACKNOWLEDGEMENT TO EX-IM POWER OF ATTORNEY TO TRADEMARK AND
PATENT SECURITY AGREEMENT)

PATENTS

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Acoustic Energy System, Method Apparatus for Processing Flat Articles	US	11/625,556	1/22/2007		
Acoustic Generating Device	US	61/034,142	3/5/2008		
Apparatus and Method for Cleaning and Drying a Hydrophobic Surface of a Substrate	US	11/755,619	5/30/2007		
Apparatus and Method for the Cleaning of Substrates	US	10/111,332	4/18/2002	11/16/2004	6,817,369
Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Same to Process Substrates	US	11/625,651	1/22/2007		
Apparatus and Method of Measuring Acoustical Energy Applied to a Substrate	US	11/837,292	8/10/2007		
Apparatus and Methods for Vapor Generation System	US	10/098,847	3/15/2002	4/20/2004	6,722,056
Apparatus for Processing Substrates in a Fluid Tank	US	09/171,757	10/23/1998	11/14/2000	6,145,520
Apparatus, System and Method for Processing a Substrate that Prohibits Air Flow Containing Contaminants and/or Residues from Depositing on the Substrate	US	11/777,256	7/12/2007		
Capillary Drying of Substrates	US	10/358,636	2/5/2003	6/21/2005	6,907,890
Centrifugal Wafer Processor	US	90/002,139	9/14/1990	1/21/1992	B1 4,571,850
Chemical Concentration Control Device	US	10/117,725	4/5/2002	7/27/2004	6,766,818
Cleaning and Drying Method and Apparatus	US	10/091,011	3/4/2002	1/4/2005	6,837,944
Compliant Silicon Wafer Handling System	US	08/825,883	4/2/1997	9/11/2001	6,286,688
Device and Method for Processing Substrates	US	09/869,213	9/22/2001	10/19/2004	6,805,754
Device and Method for the Treatment of Substrates in a Fluid Container	US	09/367,683	12/31/1999	11/18/2003	6,647,641
Device and Method for the Treating Substrates in a Fluid Container	US	08/862,890	5/23/1997	9/21/1999	5,954,068
Device for Chemical Wet Treatment	US	08/875,408	7/31/1997	5/11/1999	5,902,402
Device for Treating Substrates in a Fluid Container	US	08/761,717	12/6/1996	6/5/2001	6,240,938
Device for Wet-Treatment of Substrates	US	09/171,271	6/22/1999	8/7/2001	6,269,822
Dump Door	US	10/085,565	2/26/2002	1/18/2005	6,843,859
Facility for Treating Objects in a Process Tank	US	09/068,618	7/7/1998	2/25/2003	6,523,552
Industrial Robot Safety Device That Shuts Down Operation in Response to Variation in Tension of a Rope	US	08/851,668	5/6/1997	9/15/1998	5,807,408
Low Profile Wafer Carrier	US	10/053,449	1/17/2002	3/29/2005	6,871,657
Megasonic Cleaner and Dryer System	US	10/171,430	6/12/2002	8/16/2005	6,928,751
Megasonic Cleaner and Dryer	US	10/171,429	6/12/2002	8/2/2005	6,923,192
Megasonic Cleaner and Dryer	US	10/171,426	6/12/2002	6/29/2004	6,754,980

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Title	Country	Application Number	Application Date	Issue Date	Patent Number
Megasonic Cleaner and Dryer	US	10/864,927	6/10/2002	9/5/2006	7,100,304
Megasonic Cleaner Probe System with Gasified Fluid	US	09/906,384	7/16/2001	2/3/2004	6,684,890
Megasonic Cleaner Probe System with Gasified Fluid	US	10/742,214	12/19/2003	5/23/2006	7,047,989
Megasonic Cleaner Probe System with Gasified Fluid	US	10/864,929	6/10/2004	1/2/2007	7,156,111
Megasonic Cleaner Probe System with Gasified Fluid	US	11/595,029	11/9/2006		
Megasonic Cleaner System With Buffered Cavitation Method	US	10/341,425	1/10/2003	9/12/2006	7,104,268
Megasonic Cleaning System	US	08,277,792	7/20/1994	4/29/1997	5,625,249
Megasonic Cleaning System	US	07/791,094	11/12/1991	9/28/1993	5,247,954
Megasonic Probe Energy Attenuator	US	09/922,509	8/3/2001	1/20/2004	6,679,272
Megasonic Probe Energy Director	US	10/760,596	1/20/2004	5/17/2005	6,892,738
Megasonic Probe Energy Director	US	10/059,682	1/29/2002	10/30/2007	7,287,537
Megasonic Transducer Assembly	US	11/873,750	10/17/2007		
Megasonic Transducer Assembly	US	08/042,889	4/5/1993	11/22/1994	5,365,960
Megasonic System	US	10/117,768	4/5/2002	3/18/2003	6,532,974
Megasonic System	US	10/304,583	11/25/2002	9/30/2003	6,626,189
Membrane Dryer	US	10/117,739	4/5/2002	1/18/2005	6,842,998
Membrane Dryer	US	10/951,009	9/27/2004	8/16/2005	6,928,750
Method and Apparatus for Drying Semiconductor Wafers	US	08/275,807	7/15/1994	9/17/1996	5,556,479
Method and Apparatus for Treating Substrates	US	09/600,084	6/30/2000	8/19/2003	6,607,604
Method and System for Chemical Injection in Silicon Wafer Processing	US	10/053,364	1/18/2002	7/27/2004	6,767,877
Method and System for Processing a Substrate Using a Composite Transmitter	US	60/985,947	11/6/2007		
Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates	US	09/257,488	2/25/1999	7/17/2001	6,261,845
Method for Cavitation Measurement	US	61/031,845	2/27/2008		
Method for Post-CMP Advanced Front End of Line Cleaning	US	12/070,620	2/19/2008		
Methods for Treating Semiconductor Wafers	US	09/096,898	6/12/1998	10/26/1999	5,972,123
Nextgen Wet Process Tank	US	10/117,778	4/5/2002	1/1/2005	6,840,250
Nozzel for Use in the Megasonic Cleaning of Substrates	US	11/781,835	7/23/2007		
Process and Apparatus for Removal of Photoresist from Semiconductor Wafers Using Spray Nozzles	US	10/366,054	2/13/2003	11/16/2004	6,818,563
Process for Etching Oxide Films in a Sealed Photochemical Reactor	US	07/876,043	4/30/1992	8/10/1993	5,234,540
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	10/909,764	8/2/2004	1/30/2007	7,169,253
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	11/649,535	1/4/2007		

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Reciprocating Megasonic Probe	US	10/140,029	5/6/2002	3/6/2007	7,185,661
Reciprocating Megasonic Probe	US	11/640,718	12/18/2006		
Semiconductor Wafer Cleaning System	US	08/361,139	12/21/1994	8/12/1997	5,656,097
Semiconductor Wafer Cleaning System	US	08/908,330	8/7/1997	6/1/1999	5,908,509
Semiconductor Wafer Cleaning System	US	08/908,345	8/7/1997	12/7/1999	5,996,595
Semiconductor Wafer Cleaning System	US	08/910,033	8/11/1997	9/14/1999	5,950,645
Semiconductor Wafer Cleaning System	US	09/694,938	10/23/2000	4/30/2002	6,378,534
Single Chamber Megasonic Energy Center	US	07/598,909	10/16/1990	9/22/1992	5,148,823
Single Wafer Megasonic Semiconductor Wafer Processing System	US	07/598,426	10/16/1990	2/25/1992	5,090,432
Single Wafer Megasonic Semiconductor Wafer Processing System	US	07/809,799	12/18/1991	2/15/1994	5,286,657
Spray Jet Cleaning Apparatus and Method	US	11/745,866	5/8/2007		
Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrate	US	10/699,042	10/31/2003	10/18/2005	6,955,727
Substrate Processing Device	US	09/308,850	5/24/1999	2/20/2001	6,189,552
System and Method for Drying a Rotating Substrate	US	11/624,445	1/18/2007		
System and Method for Point-of-Use Filtration and Purification of Fluids Used in Substrate Processing	US	10/895,511	7/20/2004	12/25/2007	7,311,847
System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal	US	11/841,427	8/20/2007		
System and Method for Selective Etching a Silicon Nitride During Substrate Processing	US	10/585,229	4/20/2007		
System and Method of Cleaning Substrates Using a Subambient Process Solution	US	11/544,802	10/6/2006		
System and Method of Determining the Operating Frequency at Which to power a Transducer	US	12/059,602	3/31/2008		
System and Method of Processing Substrates Using Sonic Energy Having Cavitation Control	US	11/454,447	6/15/2006		
System for Removal of Photoresist Using Sparger	US	10/052,823	1/17/2002	11/18/2003	6,649,018
System for Removal of Photoresist Using Sparger	US	10/634,440	8/5/2003	3/8/2005	6,863,836
Transducer Assembly Incorporating a Transmitter Having Through Holes, and Method and System for Cleaning a Substrate Utilizing the Same	US	11/777,252	7/12/2007		
Vapor Drying System and Method	US	09/227,637	1/8/1999	12/11/2001	6,328,809
Vapor Jet Dryer Apparatus and Method	US	07/837,221	2/18/1992	7/13/1993	5,226,242
Wafer Cleaning System	US	08/724,518	9/30/1996	3/21/2000	6,039,059
Wafer Cleaning System	US	09/057,182	4/8/1998	10/31/2000	6,140,744

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Wafer Cleaning System	US	09/643,328	8/22/2000	10/2/2001	6,140,744
Wafer Cleaning System	US	09/953,504	9/13/2001	10/15/2002	6,463,938
Wafer Cleaning System	US	10/243,463	9/12/2002	1/27/2004	6,681,782
Wafer Cleaning System	US	10/243,486	9/12/2002	2/3/2004	6,684,891
Wafer Cleaning System	US	10/726,774	12/3/2003	10/10/2006	7,117,876
Wafer Cleaning System	US	11/375,907	3/15/2006	9/11/2007	7,268,469
Wafer Cleaning System	US	11/386,634	3/22/2006	5/1/2007	7,211,932
Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	US	09/324,813	8/16/2007		
	US		6/21/1999		

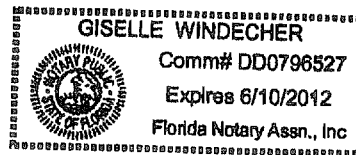
COMPANY ACKNOWLEDGMENT

UNITED STATES OF AMERICA :
STATE OF Florida : SS
COUNTY OF Miami Dade :

On this 2nd of September 2008, before me personally appeared Adam Schmel, to me known and being duly sworn, deposes and says that s/he is authorized to sign on behalf of Wafer Holdings, Inc., a Delaware corporation; that s/he signed the Agreement thereto pursuant to the authority vested in him/her by law; that the within Agreement is the voluntary act of such company; and s/he desires the same to be recorded as such.

[Signature]
Notary Public

My Commission Expires: 6/10/12



(ACKNOWLEDGEMENT TO EXPORT-IMPORT TRADEMARK AND PATENT SECURITY
AGREEMENT)

POWER OF ATTORNEY

WAFER HOLDINGS, INC. (the "Grantor"), hereby authorizes PNC BANK, NATIONAL ASSOCIATION, its successors and assigns, and any officer or agent thereof (collectively, "Agent"), as agent for the Lenders under that certain Export-Import Revolving Credit and Security Agreement among Agent, the financial institutions which are now or which hereafter become a party thereto as lenders (the "Lenders") and Grantor dated as of September __, 2008 (as it may hereafter be amended, modified, restated or replaced from time to time, the "Loan Agreement"), following the occurrence and during the continuance of an Event of Default (as defined in the Loan Agreement) as the true and lawful attorney-in-fact of Grantor, with the power to endorse the name of Grantor on all applications, assignments, documents, papers and instruments necessary for Agent to enforce and effectuate its rights under that certain Trademark and Patent Security Agreement between Grantor and Agent dated the date hereof (as it may hereafter be supplemented, restated, superseded, amended or replaced, the "Trademark and Patent Security Agreement"), including, without limitation, the power to record its interest in any trademarks and patents (as defined in the Trademark and Patent Security Agreement) or additional trademarks and patents in the United States Patent and Trademark Office or other appropriate governmental office including, without limitation, the power to execute on behalf of Grantor a supplement to the Trademark and Patent Security Agreement, to use the Trademarks and Patents or to grant or issue any exclusive or non-exclusive license under the Trademarks and Patents to anyone else, or to assign, pledge, convey or otherwise transfer title in or dispose of the Trademarks and Patents to anyone else including, without limitation, the power to execute on behalf of Grantor a trademark, patent, or copyright assignment, in each case subject to the terms of the Trademark and Patent Security Agreement. Nothing herein contained shall obligate Agent to use or exercise any rights granted herein.

This Power of Attorney is given and any action taken pursuant hereto is intended to be so given or taken pursuant to and subject to the provisions of the Loan Agreement.

Grantor hereby unconditionally ratifies all that such attorney shall lawfully do or cause to be done following the occurrence and during the continuance of an Event of Default by virtue hereof and in accordance with the terms of the Trademark and Patent Security Agreement, the Loan Agreement and the Other Documents.

This Power of Attorney shall be irrevocable for the life of the Trademark and Patent Security Agreement.

[SIGNATURES TO APPEAR ON FOLLOWING PAGE]

IN WITNESS WHEREOF, Grantor has executed this Power of Attorney as of the date stated above.

WAFER HOLDINGS, INC.

By: Ad Schmet
Name: Adlan Schmet
Title: Director

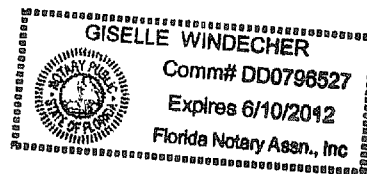
(SIGNATURE PAGE TO POWER OF ATTORNEY TO EX-IM TRADEMARK AND PATENT
SECURITY AGREEMENT)

COMPANY ACKNOWLEDGMENT

UNITED STATES OF AMERICA :
STATE OF Florida : SS
COUNTY OF Maricopa :

On this 22 of September, 2008, before me personally appeared Adam Schindel to me known and being duly sworn, deposes and says that s/he is authorized to sign on behalf of Wafer Holdings, Inc., that s/he signed the Agreement thereto pursuant to the authority vested in him by law; that the within Agreement is the voluntary act of such company; and s/he desires the same to be recorded as such.

Giselle Windecher
Notary Public
My Commission Expires: 6/10/12



(ACKNOWLEDGEMENT TO EX-IM POWER OF ATTORNEY TO TRADEMARK AND
PATENT SECURITY AGREEMENT)